

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	93	257/633.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L2	657	257/635.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L3	181	257/646.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L4	380	257/649.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L5	1065	257/675.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L6	2019	257/706.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L7	273	257/e23.001.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L8	283	((naota or iwao) near2 nakamura).inv. or (tomoharu near2 shimada). inv. or (kenichi near2 ishiguro).inv. or (sadao near2 nakashima).inv.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L9	25971	thermal adj treatment and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21

L10	6	L8 and L9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L11	7960	(HITACHI adj KOKUSAI adj ELECTRIC).as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L12	45	L9 and L11	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L13	12	(substrate near5 (support or board or plate)) near10 (10mm)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L14	10	(substrate near10 (support or board or plate)) near15 (thickness near10(10mm))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L15	8	L14 not L13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:21
L17	16	furnace with substrate with (holder support board) near15 (thickness)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:30
L19	155554	((heat thermal anneal\$2) near15 treatment and substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:32
L20	47285	((heat thermal anneal\$2) near15 treatment) with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:32
L21	3400	(furnace chamber) with ((heat thermal anneal\$2) near15 treatment) with substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:33

L22	17784	(furnace chamber) with (heat thermal anneal\$2) near15 substrate	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:34
L23	2224	(furnace chamber) with (heat thermal anneal\$2) near15 substrate with (silicon si)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:35
L24	1234	I23 and @ad<="20020927"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/09/24 14:36

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